

Fig.2

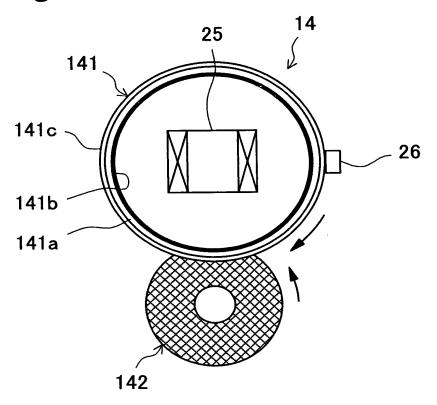


Fig.3

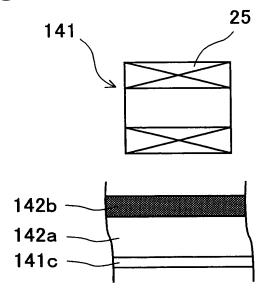
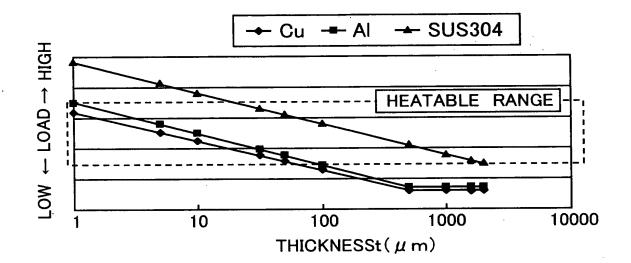
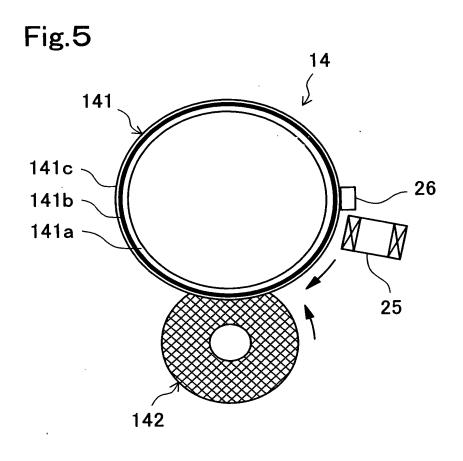


Fig.4





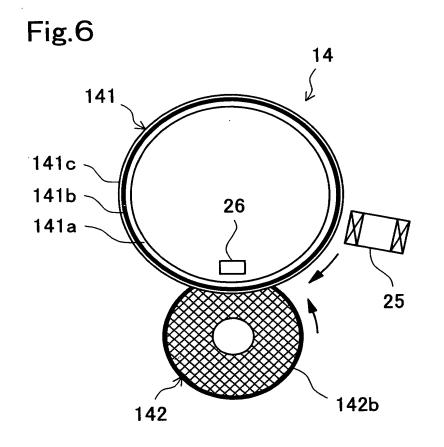


Fig.7

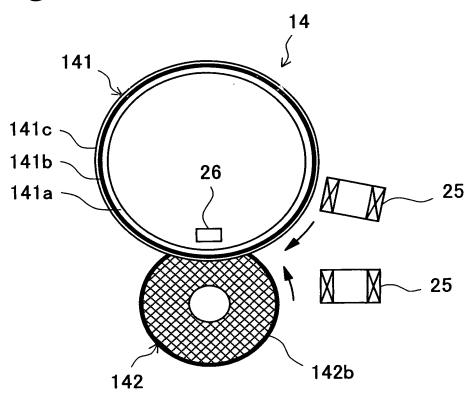


Fig.8

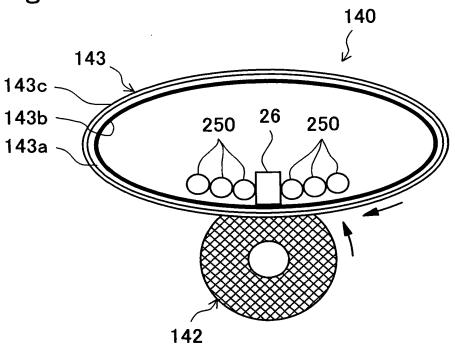


Fig.9

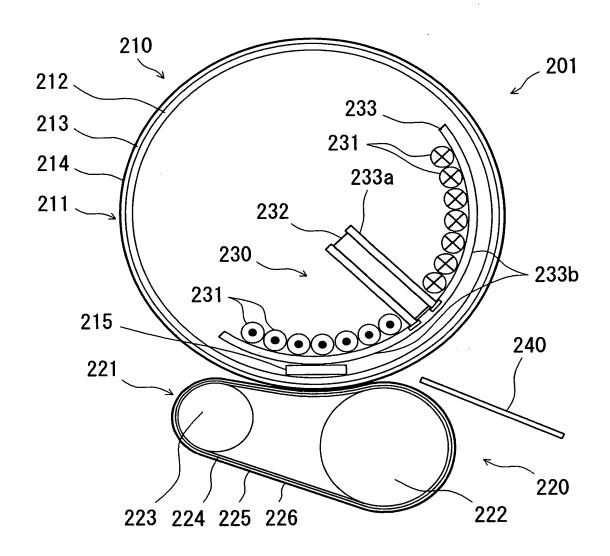


Fig.10

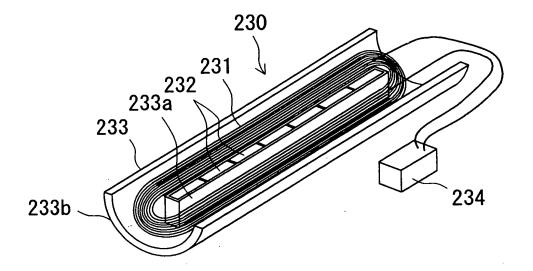


Fig.11

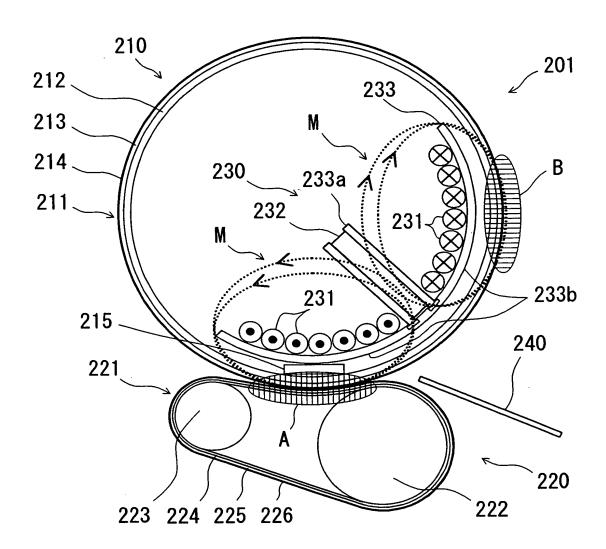


Fig. 12

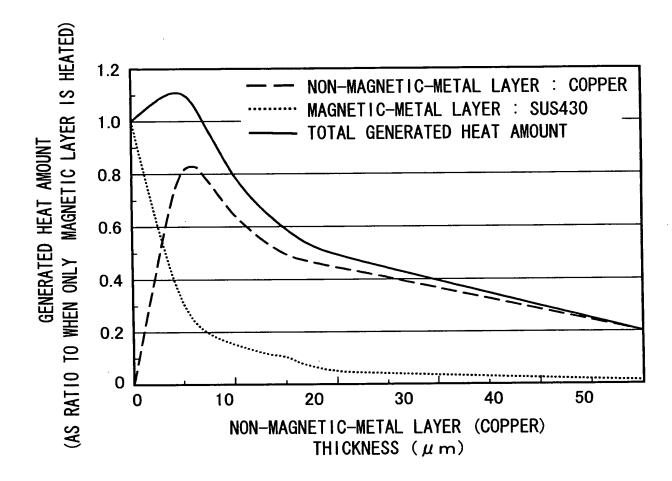


Fig. 13

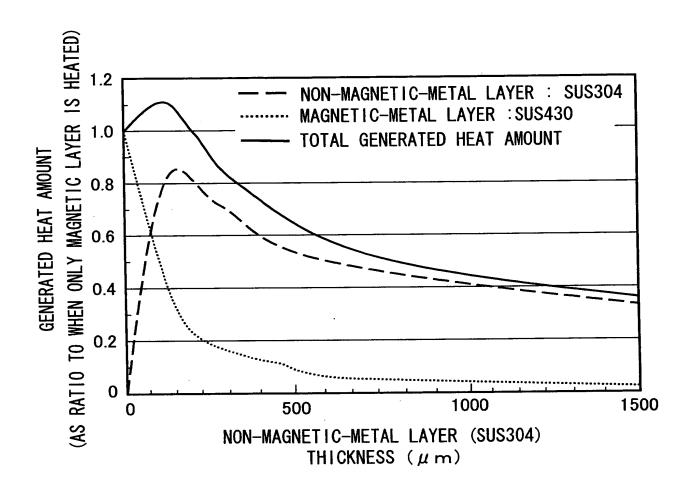


Fig. 14

DAD R THICKNESS (μm) COPPER SUS304 0.0 0.0 2.1 90 2.9 125 5.0 215 6.0 250 7.0 300 10 431	WE	(AS RATIO 10 WHEN UNLY MAGNETIC	MAGNETIC
THICKNESS (μm) COPPER SUS304 0.0 0.0 0.0 2.1 90 2.9 125 5.0 215 6.0 250 7.0 300 10 431		METAL LAYER IS HEATED)	TED)
COPPER 0.0 2.1 2.9 5.0 6.0 6.0 10	NON-MAGNETIC LAYER	MAGNETIC LAYER	TOTAL HEAT
0.0 2.1 2.9 5.0 6.0 6.0 7.0 10	COPPER or SUS304	SUS430	AMOUNI
2. 1 2. 9 5. 0 6. 0 7. 0 10	0.00	1.00	1.00
2.9 5.0 6.0 7.0 10	0.35	0.70	1.05
5.0 6.0 7.0 10	0.55	0.55	1.10
6.0 7.0 10	0.80	0.30	1.10
7.0 10 15	0.80	0.30	1.10
10	0.80	0. 20	1.00
15	0.65	0. 15	0.80
	0.50	0.10	09 .0
8. 35 × 10 ⁻⁴ 20 862	0. 45	0.05	0.50
3.34×10 ⁻⁴ 50 2155	0.20	0.01	0.21

Fig. 15

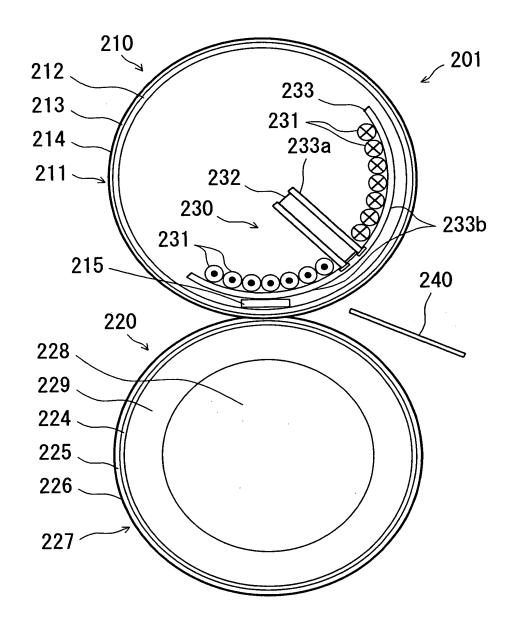


Fig. 16

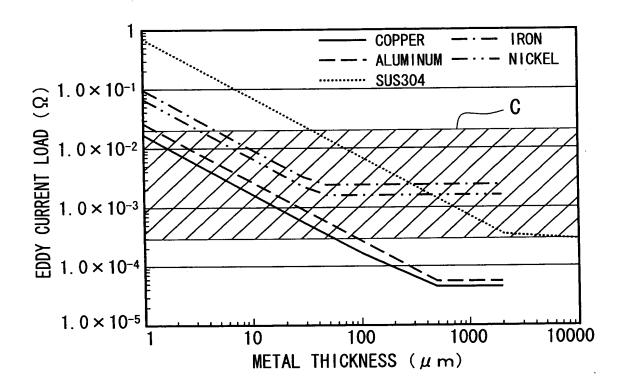


Fig. 17

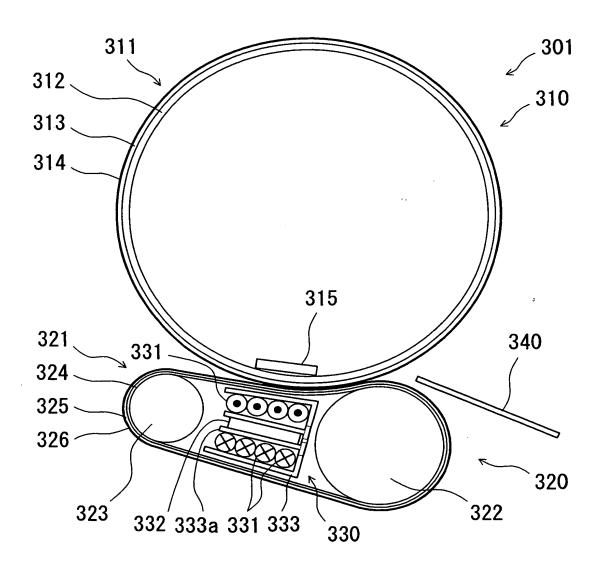


Fig. 18

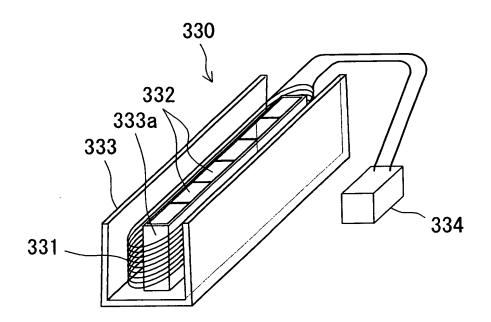


Fig. 19

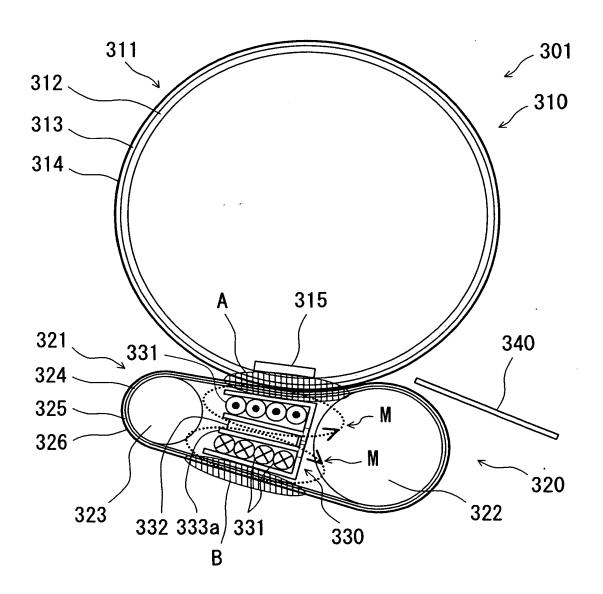


Fig. 20

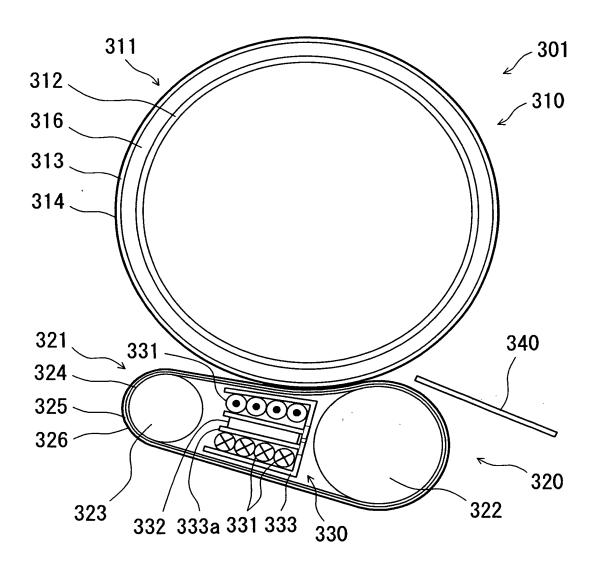


Fig. 21

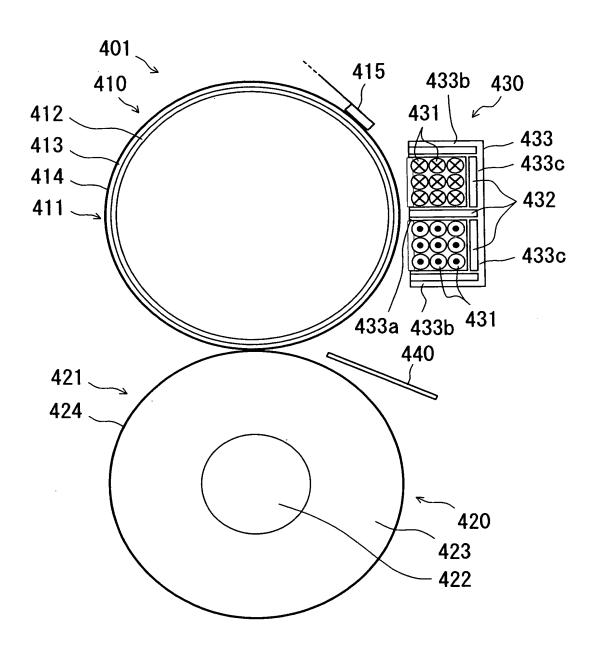


Fig. 22

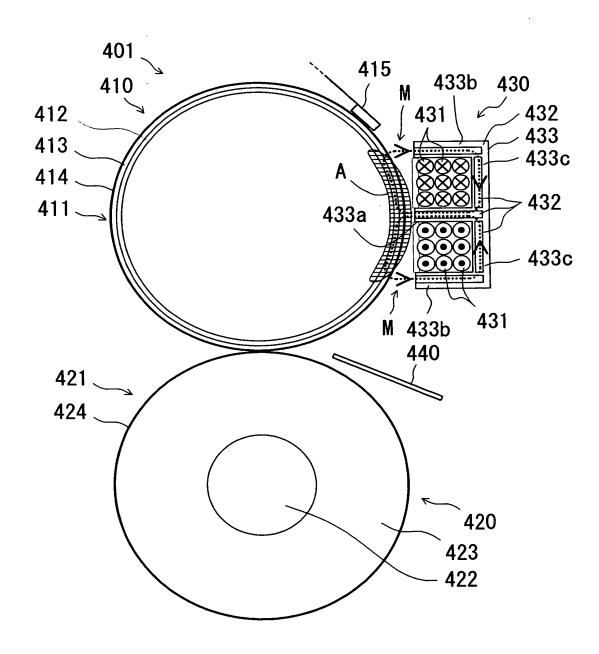


Fig. 23

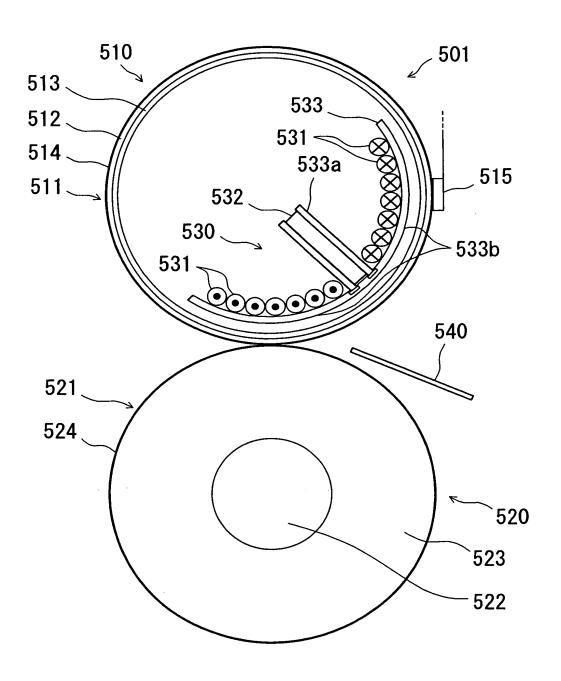


Fig. 24

